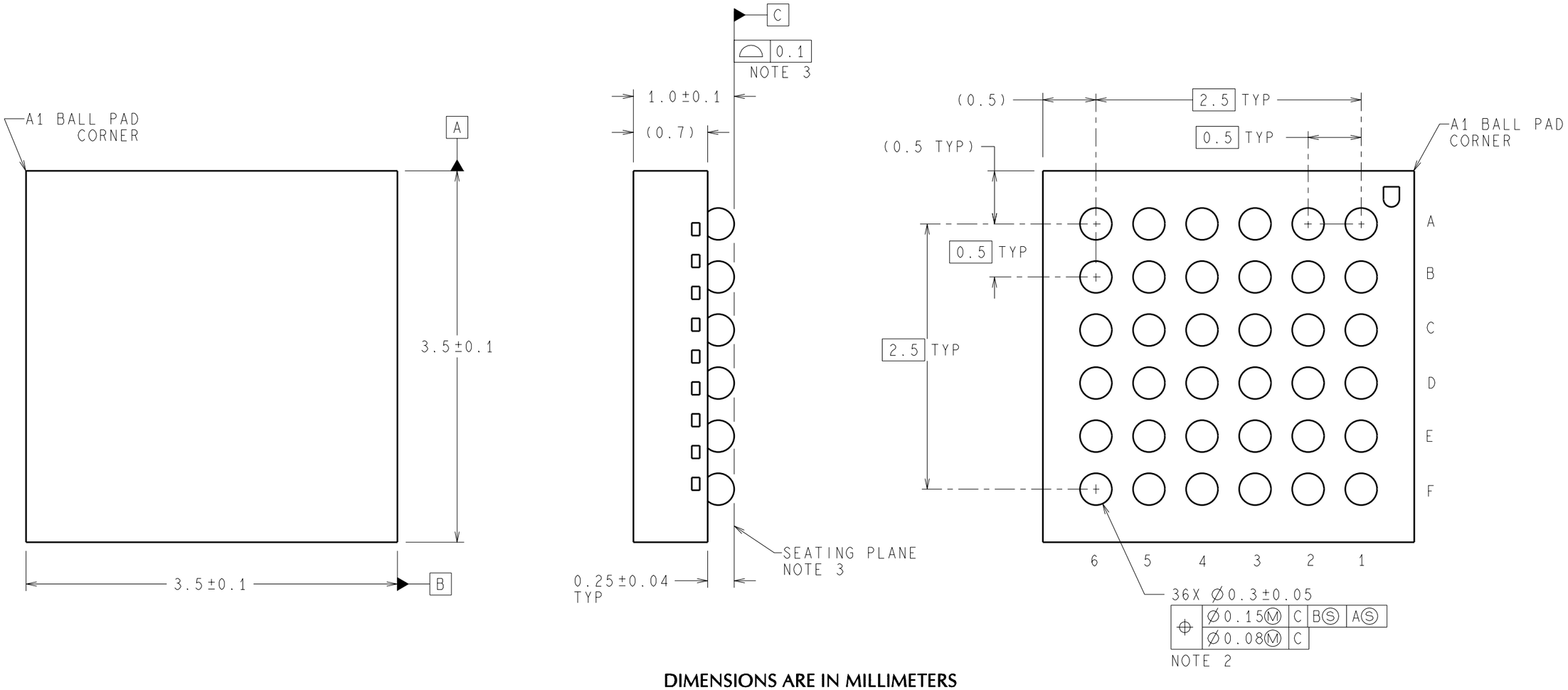
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1386	03/25/2004	TL/AP



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR SOLDER BALL COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
3. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF MARCH 2004.

APPROVALS	DATE
DRAWN T LEQUANG	03/25/2004
DFTG. CHK. MARTA SUCHY	03/25/2004
ENGR. CHK. ASHOK PRABHU	03/25/2004

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

MICRO-ARRAY, 3.5x3.5x1mm BODY, 36 BALL, 0.5mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-GRA36A	A

FORMERLY: N/A SHEET 1 of 1